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May 7, 2025

David Laisa
Kenya Medical Supplies Authority (KEMSA)
P.O. Box 47715 - 00100
Nairobi, Kenya

Dear Mr. David Laisa,

I am an enthusiastic BSc Electrical and Telecommunication Engineering student at Multimedia University of Kenya, expected to graduate in December 2027. I am writing to you regarding potential attachment opportunities at KEMSA, as recommended by Mr Kelvin kariuki. This can help me apply my skills and gain industry experience in the field of networking, datacom and telecommunications. I will be available from early June for three months according to my academic calendar.

Throughout my academic journey, I have actively gained hands-on experience to complement my coursework. I have carried out a wide range of practical labs using Huawei eNSP, including IPv4/IPv6 routing, OSPF, VLANs, Spanning Tree, ACLs, NAT, DHCP, WLANs, and more. You can view these labs in detail here: github.com/plochoidysis-ojwege/eNSP-labs.

I possess technical proficiency in TCP/IP, OSPF, VLANs, MATLAB, AutoCAD, and Python and C programming which are vital for my field in the industry. My participation in the IEEE Student Branch has helped me embrace teamwork, leadership, and communication skills.

I am excited about the opportunity to contribute to a forward thinking organization and continue building on the skills and knowledge I've developed. Thank you for considering my application. I would appreciate the chance to further discuss how I can contribute value as an intern.

Sincerely,

Onyango Denzel Ninga

encl: Curriculum Vitae